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IN THE ABSTRACT:

Please replace the Abstract of the Disclosure originally filed with the above-identified patent application with the following Abstract:

ABSTRACT OF THE DISCLOSURE

A laminated ceramic electronic component includes a plurality of conductor pattern layers (2, 3, and 4) for a coil overlapsarranged to overlap each other to form substantially U-shaped conductors (2A, 3A, and 4A) for the coil. The conductors (2A, 3A, and 4A) for the coil are electrically connected in series withthrough via holes (15) for interinner layer connection provided in ceramic green sheets (10 and 11) to form a spiral coil (L). A plurality of leading conductor pattern layers (5 and 6) also overlaps each other to form leading conductors (5A and 6A). One leading conductor pattern layer (5) is disposed per a predetermined number of conductor pattern layers (2) for the coil. An end (51) of each leading conductor pattern layer (5) is in contact with the corresponding conductor pattern layer (2) for the coil. In other words, the thickness of the leading conductors (5A and 6A) is smallerless than the thickness of the conductors (2A to 4A) for the coil.